

Vishay Siliconix

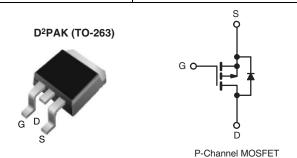
RoHS'

COMPLIANT

HALOGEN FREE

Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	- 100			
R _{DS(on)} (Ω)	V _{GS} = - 10 V 0.60			
Q _g (Max.) (nC)	18			
Q _{gs} (nC)	3.0			
Q _{gd} (nC)	9.0			
Configuration	Single			



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- P-Channel
- 175 °C Operating Temperature
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK (TO-263) is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK (TO-263) is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

ORDERING INFORMATION					
Package	D ² PAK (TO-263)	D ² PAK (TO-263)	D ² PAK (TO-263)		
Lead (Pb)-free and Halogen-free	SiHF9520S-GE3	SiHF9520STRL-GE3 ^a	SiHF9520STRR-GE3 ^a		
Lead (Pb)-free	IRF9520SPbF	IRF9520STRLPbFa	IRF9520STRRPbFa		
	SiHF9520S-E3	SiHF9520STL-E3a	SiHF9520STR-E3a		

Note

See device orientation.

ABSOLUTE MAXIMUM RATINGS (To	; = 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	- 100	V	
Gate-Source Voltage			V_{GS}	± 20	7 v	
Continuous Drain Current $V_{GS} \text{ at - 10 V} \frac{T_C = 25 ^{\circ}\text{C}}{T_C = 100 ^{\circ}\text{C}}$			I _D	- 6.8		
				- 4.8	Α	
Pulsed Drain Current ^a			I _{DM}	- 27	1	
Linear Derating Factor				0.40	W/°C	
Linear Derating Factor (PCB Mount)e				0.025	VV/ C	
Single Pulse Avalanche Energy ^b			E _{AS}	300	mJ	
Avalanche Current ^a			I _{AR}	- 6.8	А	
Repetiitive Avalanche Energy ^a			E _{AR}	6.0	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$		P _D	60	W		
Maximum Power Dissipation (PCB Mount) ^e $T_A = 25 ^{\circ}\text{C}$			3.7] vv		
Peak Diode Recovery dV/dt ^c			dV/dt	- 5.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature) for 10 s			<u> </u>	300 ^d	1	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 25 V, starting T_J = 25 °C, L = 9.7 mH, R_g = 25 Ω , I_{AS} = 6.8 A (see fig. 12).
- c. $I_{SD} \le -6.8 \text{ A}$, $dI/dt \le 110 \text{ A/}\mu\text{s}$, $V_{DD} \le V_{DS}$, $T_{J} \le 175 \,^{\circ}\text{C}$.
- d. 1.6 mm from case.
- e. When mounted on 1" square PCB (FR-4 or G-10 material).

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

IRF9520S, SiHF9520S

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Maximum Junction-to-Ambient (PCB Mount) ^a	R _{thJA}	-	40	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	2.5		

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	= 0, I _D = - 250 μA	- 100	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = - 1 mA	-	- 0.1	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = - 250 μA	- 2.0	-	- 4.0	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}		- 100 V, V _{GS} = 0 V /, V _{GS} = 0 V, T _J = 150 °C	-	-	- 100 - 500	μA
Drain-Source On-State Resistance	R _{DS(on)}		I _D = - 4.1 A ^b	-	-	0.60	Ω
Forward Transconductance	9 _{fs}	V _{DS} =	- 50 V, I _D = - 4.1 A ^b	2.0	-	-	S
Dynamic		1		I.	ı		
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	390	-	
Output Capacitance	C _{oss}		$V_{DS} = -25 V$,	-	170	-	рF
Reverse Transfer Capacitance	C _{rss}	f = 1	.0 MHz, see fig. 5	-	45	-	
Total Gate Charge	Qg				-	18	
Gate-Source Charge	Q _{gs}	V _{GS} = - 10 V	$I_D = -6.8 \text{ A}, V_{DS} = -80 \text{ V},$ see fig. 6 and 13 ^b	-	-	3.0	nC
Gate-Drain Charge	Q _{gd}		see fig. 6 and 13°		-	9.0	1
Turn-On Delay Time	t _{d(on)}	V_{DD} = - 50 V, I_{D} = - 6.8 A, R_{G} = 18 Ω, R_{D} = 7.1 Ω, see fig. 10 ^b		-	9.6	-	ns
Rise Time	t _r			-	29	-	
Turn-Off Delay Time	t _{d(off)}			-	21	-	
Fall Time	t _f			-	25	-	
Internal Drain Inductance	L _D		Between lead, 6 mm (0.25") from		4.5	-	mll
Internal Source Inductance	L _S	package and center of die contact		-	7.5	-	nH
Drain-Source Body Diode Characteristic	s	•					
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the		-	-	- 6.8	Α
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction diode		-	-	- 27	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = - 6.8 A, V _{GS} = 0 V ^b		-	-	- 6.3	V
Body Diode Reverse Recovery Time	t _{rr}	- T _J = 25 °C, I _F = - 6.8 A, dl/dt = 100 A/μs ^b		-	98	200	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.33	0.66	μC
Forward Turn-On Time	t _{on}	Intrinsic tu	ırn-on is dominated by L _S and L _D)			L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

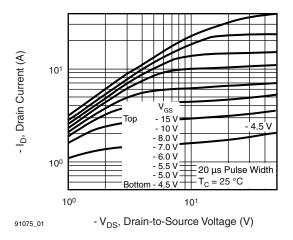


Fig. 1 - Typical Output Characteristics, $T_C = 25$ °C

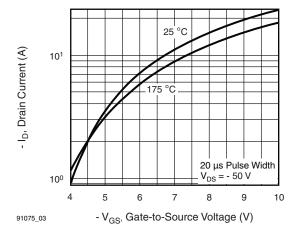


Fig. 3 - Typical Transfer Characteristics

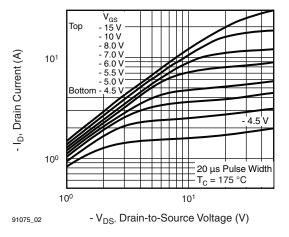


Fig. 2 - Typical Output Characteristics, T_C = 175 °C

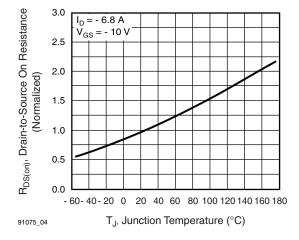
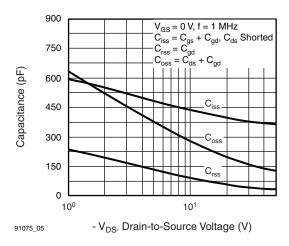


Fig. 4 - Normalized On-Resistance vs. Temperature

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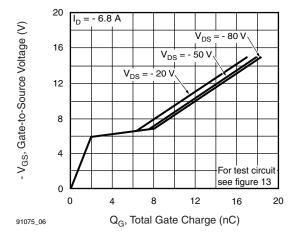




10⁻¹
10

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 7 - Typical Source-Drain Diode Forward Voltage



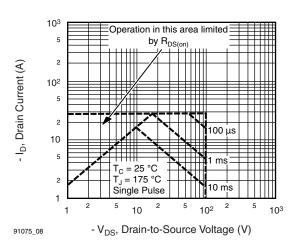


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

Fig. 8 - Maximum Safe Operating Area





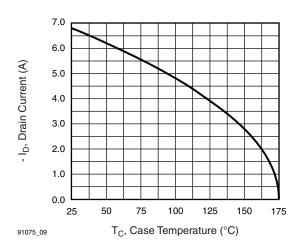


Fig. 9 - Maximum Drain Current vs. Case Temperature

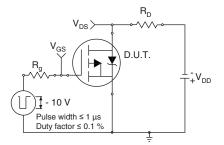


Fig. 10a - Switching Time Test Circuit

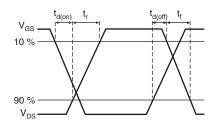


Fig. 10b - Switching Time Waveforms

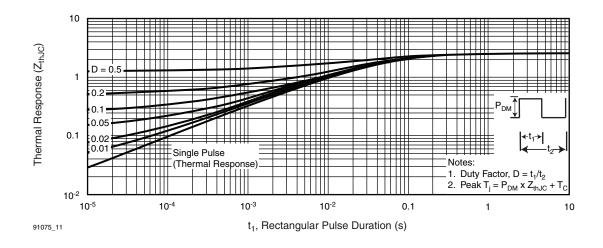


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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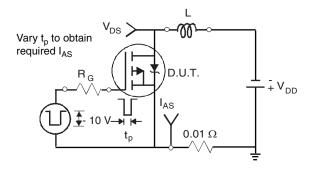


Fig. 12a - Unclamped Inductive Test Circuit

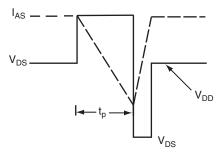


Fig. 12b - Unclamped Inductive Waveforms

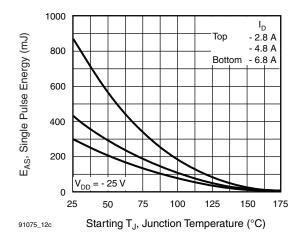


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

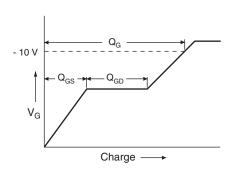


Fig. 13a - Basic Gate Charge Waveform

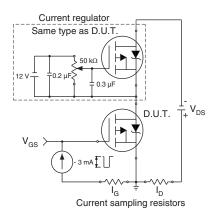
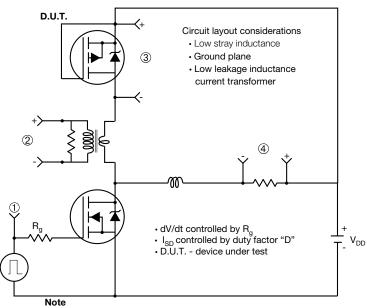


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



· Compliment N-Channel of D.U.T. for driver

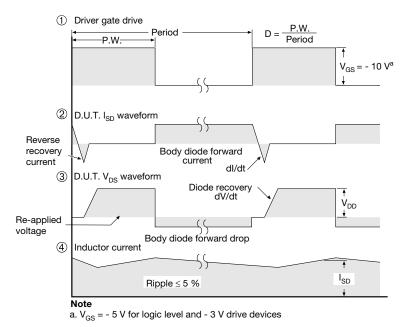


Fig. 14 - For P-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91075.





TO-263AB (HIGH VOLTAGE)







	MILLIN	METERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
С	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
Е	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	ı
е	2.54 BSC		0.100 BSC	
Н	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	ı	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010	BSC
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08

DWG: 5970

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
- 4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
- 5. Dimension b1 and c1 apply to base metal only.
- 6. Datum A and B to be determined at datum plane H.
- 7. Outline conforms to JEDEC outline to TO-263AB.

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Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

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AMEYA360 Components Supply Platform

Authorized Distribution Brand:

























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